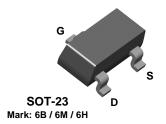


2N5484 2N5485 2N5486

### **MMBF5484 MMBF5485 MMBF5486**





NOTE: Source & Drain are interchangeable

#### **N-Channel RF Amplifier**

This device is designed primarily for electronic switching applications such as low On Resistance analog switching. Sourced from Process 50.

#### **Absolute Maximum Ratings\***

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{DG}$	Drain-Gate Voltage	25	V
$V_{GS}$	Gate-Source Voltage	- 25	V
I <sub>GF</sub>	Forward Gate Current	10	mA
T <sub>J</sub> ,T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

1) These ratings are based on a maximum junction temperature of 150 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

#### Thermal Characteristics TA = 25°C unless otherwise noted

Symbol	Characteristic	N	Units	
		2N5484-5486	*MMBF5484-5486	
P <sub>D</sub>	Total Device Dissipation	350	225	mW
	Derate above 25°C	2.8	1.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	556	°C/W

<sup>\*</sup>Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

# N-Channel RF Amplifier (continued)

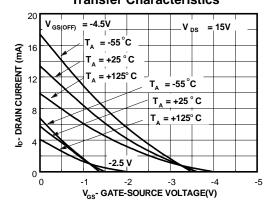
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
OFF CHAI	RACTERISTICS					
V <sub>(BR)GSS</sub>	Gate-Source Breakdown Voltage	I <sub>G</sub> = - 1.0 μA, V <sub>DS</sub> = 0	- 25			V
I <sub>GSS</sub>	Gate Reverse Current	V <sub>GS</sub> = - 20 V, V <sub>DS</sub> = 0	1		- 1.0	nA
		V <sub>GS</sub> = - 20 V, V <sub>DS</sub> = 0, T <sub>A</sub> = 100°C V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 nA <b>5484</b>			- 0.2	μΑ
$V_{GS(off)}$	Gate-Source Cutoff Voltage	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 nA <b>5484 5485</b>	- 0.3 - 0.5		- 3.0 - 4.0	V
		5486	- 2.0		- 6.0	V
ON CHAR	ACTERISTICS					
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current*	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 <b>5484</b>	1.0		5.0	mA
200	3	5485	4.0		10	mA
		5486	8.0		20	mA
SMALL SI	GNAL CHARACTERISTICS	T	T	1		_
<b>g</b> fs	Forward Transfer Conductance	$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 1.0 \text{ kHz}$ 5484	3000		6000	μmhos
		5485	3500		7000	μmhos
		5486	4000		8000	μmhos
Re <sub>(yis)</sub>	Input Conductance	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0, f = 100 MHz <b>5484</b>			100	μmhos
		$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 400 \text{ MHz}$			100	μιπιοε
		5485 / 5486			1000	μmhos
g <sub>os</sub>	Output Conductance	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0, f = 1.0 kHz <b>5484</b>			50	μmhos
		5485			60	μmhos
_		5486			75	μmhos
Re <sub>(yos)</sub>	Output Conductance	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0, f = 100 MHz <b>5484</b>			75	μmhos
		$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 400 \text{ MHz}$			'	μιιιου
_	- I- I-	5485 / 5486			100	μmhos
Re <sub>(yfs)</sub>	Forward Transconductance	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0, f = 100 MHz <b>5484</b>	2500			μmhos
		$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 400 \text{ MHz}$				μιιιου
		5485 5486	3000 3500			μmhos
Ciss	Input Capacitance	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0, f = 1.0 MHz	3300		5.0	μmhos pF
Crss	Reverse Transfer Capacitance	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0, f = 1.0 MHz	1		1.0	pF
Coss	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 1.0 \text{ MHz}$	†		2.0	pF
NF	Noise Figure	$V_{DS}$ = 15 V, $R_{G}$ = 1.0 k $\Omega$ , f = 100 MHz 5484			3.0	dB
		$V_{DS}$ = 15 V, $R_G$ = 1.0 k $\Omega$ , f = 400 MHz 5484		4.0		dB
		$V_{DS} = 15 \text{ V}$ , $R_{G} = 1.0 \text{ k}\Omega$ ,				
		f = 100 MHz 5485 / 5486			2.0	dB
		$V_{DS} = 15 \text{ V}, R_G = 1.0 \text{ k}\Omega,$	II.		1	

<sup>\*</sup>Pulse Test: Pulse Width  $\leq$  300 ms, Duty Cycle  $\leq$  2%

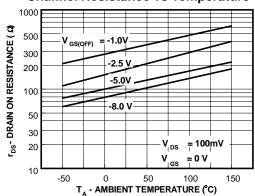
(continued)

#### **Typical Characteristics**

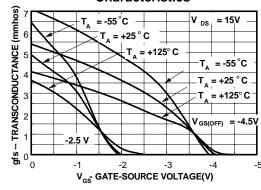




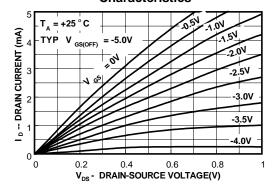
#### **Channel Resistance vs Temperature**



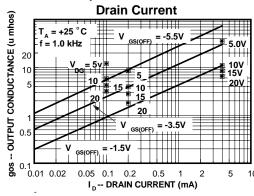
Transconductance Characteristics



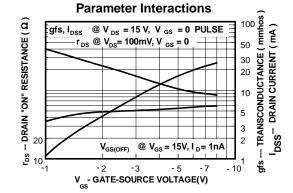
Common Drain-Source Characteristics



Output Conductance vs

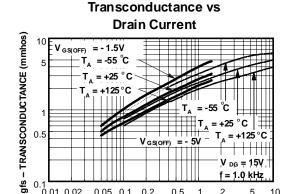


Transconductance
Parameter Interaction



(continued)

#### Typical Characteristics (continued)

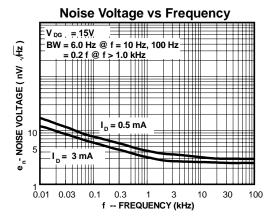


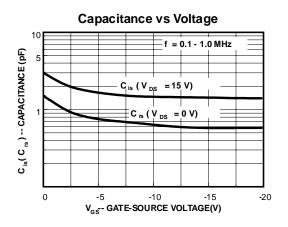
0.2

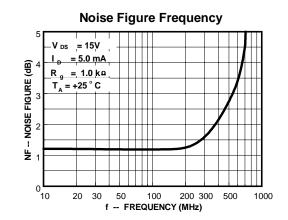
0.5 ID - DRAIN CURRENT (mA)

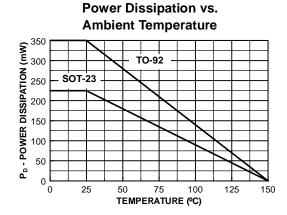
0.1 0.02

0.05 0.1



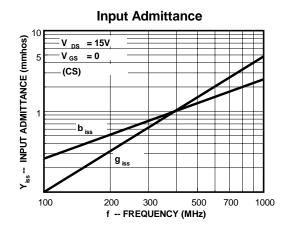


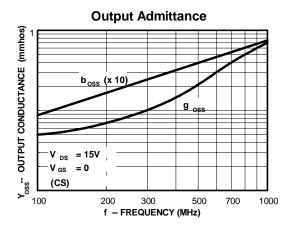


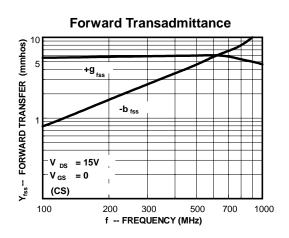


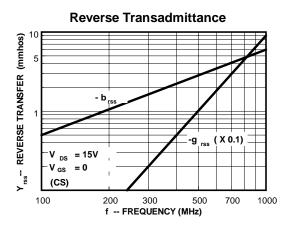
(continued)

#### **Common Source Characteristics**



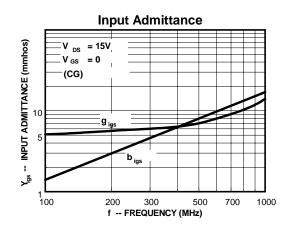


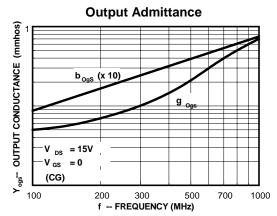




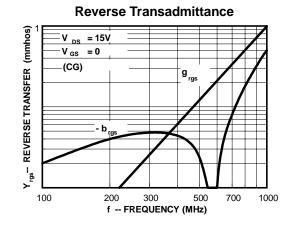
(continued)

#### **Common Gate Characteristics**





#### 



#### **TO-92 Tape and Reel Data** FAIRCHILD SEMICONDUCTOR TM **TO-92 Packaging** Configuration: Figure 1.0 **TAPE and REEL OPTION** FSCINT Label sample See Fig 2.0 for various Reeling Styles CBVK//418019 **FSCINT** Label 5 Reels per Intermediate Box Customized F63TNR Label sample Label F63TNR LOT: CBVK741B019 QTY: 2000 FSID: PN222N Customized QTY1: QTY2: Label 375mm x 267mm x 375mm Intermediate Box TO-92 TNR/AMMO PACKING INFROMATION **AMMO PACK OPTION** See Fig 3.0 for 2 Ammo Packing Style Quantity EOL code **Pack Options** 2,000 D26Z Е 2,000 D27Z Ammo М 2,000 D74Z D75Z 2,000 **FSCINT** Unit weight = 0.22 gm Reel weight with components = 1.04 kg Ammo weight with components = 1.02 kg Max quantity per intermediate box = 10,000 units Label 5 Ammo boxes per Intermediate Box 327mm x 158mm x 135mm Immediate Box Customized F63TNR Customized Label Label 333mm x 231mm x 183mm Intermediate Box (TO-92) BULK PACKING INFORMATION **BULK OPTION** See Bulk Packing DESCRIPTION QUANTITY Information table J18Z TO-18 OPTION STD 2.0 K / BOX Anti-static Bubble Sheets TO-5 OPTION STD NO LEAD CLIP 1.5 K / BOX J05Z **FSCINT Label** NO EOL TO-92 STANDARD STRAIGHT FOR: PKG 92, NO LEADCLIP 2.0 K / BOX 94 (NON PROELECTRON SERIES), 96 TO-92 STANDARD STRAIGHT FOR: PKG 94 (PROELECTRON SERIES BCXXX, BFXXX, BSRXXX), 97, 98 L34Z NO LEADCLIP 2.0 K / BOX 2000 units per 114mm x 102mm x 51mm EO70 box for std option Immediate Box 5 EO70 boxes per intermediate Box 530mm x 130mm x 83mm Customized Intermediate box Label FSCINT Label 10,000 units maximum per intermediate box for std option

#### TO-92 Tape and Reel Data, continued

#### **TO-92 Reeling Style** Configuration: Figure 2.0

#### Machine Option "A" (H)



Style "A", D26Z, D70Z (s/h)

# Machine Option "E" (J)

Style "E", D27Z, D71Z (s/h)

#### **TO-92 Radial Ammo Packaging** Configuration: Figure 3.0



FIRST WIRE OFF IS EMITTER (ON PKG. 92) ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON BOTTOM



FIRST WIRE OFF IS COLLECTOR (ON PKG. 92) ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON TOP



#### **TO-92 Package Dimensions**



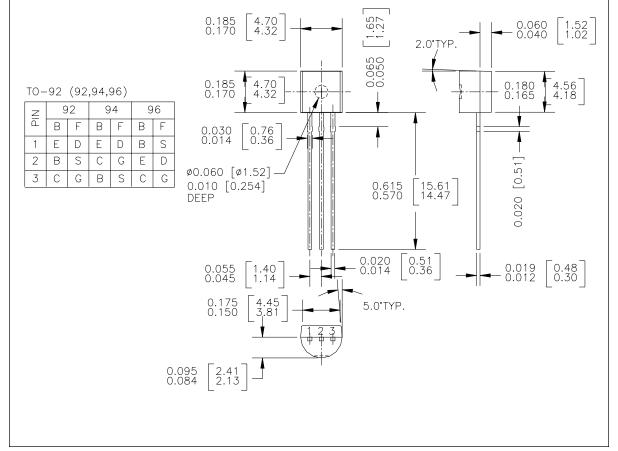
# TO-92 (FS PKG Code 92, 94, 96)





Scale 1:1 on letter size paper
Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.1977

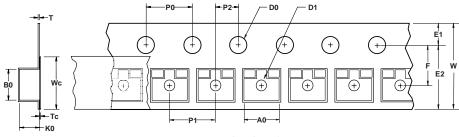




#### SOT-23 Tape and Reel Data, continued

#### **SOT-23 Embossed Carrier Tape**

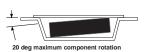
Configuration: Figure 3.0



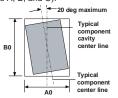
User Direction of Feed	

	Dimensions are in millimeter													
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	Т	Wc	Тс
<b>SOT-23</b> (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

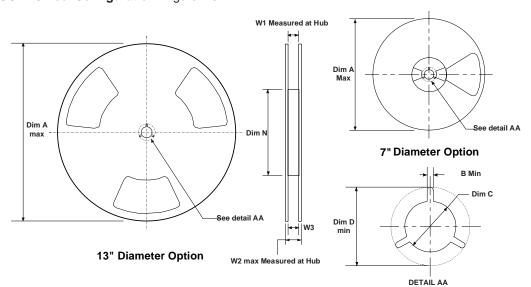


Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

#### SOT-23 Reel Configuration: Figure 4.0



	Dimensions are in inches and millimeters								
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9



# SOT-23 (FS PKG Code 49)

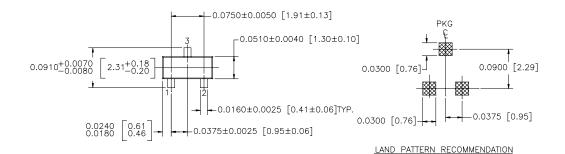


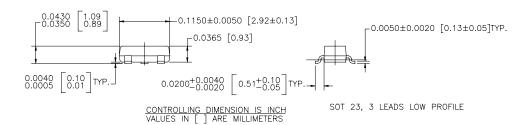


Scale 1:1 on letter size paper

Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 0.0082





NOTE: UNLESS OTHERWISE SPECIFIED

- 1. STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
- 2. REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE G, DATED JUL 1993

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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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